

Part Description:		AS4C32M32MD1-5BCN / AS4C32M32MD1-5BIN									
Weight (mg):		153.87 mg									
No.	Part Name	Material Name	Material mass (mg)	Substance in Materials	CAS Number	Element wt (%)	Element wt (mg)	wt % of total unit wt	PPM		
1	Chip	Silicon	16.21	Silicon	7440-21-3	99.68%	16.1585	10.4965%	996820		
				Aluminum	7429-90-5	0.15%	0.0242	0.0157%	1490		
				Tungston	7440-33-7	0.11%	0.0172	0.0112%	1060		
				Titanium	7440-32-6	0.042%	0.0068	0.0044%	420		
				Boron	7440-42-8	0.0060%	0.0010	0.0006%	60		
				Arsenic	7440-38-2	0.0030%	0.0005	0.0003%	30		
				Phosphorous	7723-14-0	0.0040%	0.0006	0.0004%	40		
				Copper	7440-50-8	0.0050%	0.0008	0.0005%	50		
				Fluorine	7782-41-4	0.0030%	0.0005	0.0003%	30		
				2	Substrate (SIMMTECH)	CCL-HL832NX(A-HS)	13.1464	Bismaleimide	105391-33-1	12.500%	1.6433
Triazine resin	25722-66-1	12.500%	1.6433					1.0675%	125000		
Epoxy Resin	9003-36-5	12.500%	1.6433					1.0675%	125000		
Inorganic filler	21645-51-2	37.500%	4.9299					3.2025%	375000		
Continuous Filament Fiber Glass	65997-17-3	25.000%	3.2866					2.1350%	250000		
copper foil	25.2397	Copper	7440-50-8					100.000%	25.2397	16.4000%	1000000
AUS308 (PSR-4000/CA-40)	7.4948	Acrylic resin	Trade Secret			30.00%	2.2484	1.4610%	300000		
		Barium Sulfate	7727-43-7			20.70%	1.5514	1.0081%	207000		
		3-Methoxy-3-Methyl Butyl-Acetate	103429-90-9			10.35%	0.7757	0.5040%	103500		
		Dipropylene glycol monomethyl ether	34590-94-8			12.85%	0.9631	0.6258%	128500		
		Talc containing no asbestiform fibers	14807-96-6			0.35%	0.0262	0.0170%	3500		
		photopolymerization	Trade Secret			0.35%	0.0262	0.0170%	3500		
		Solvent naphtha	64742-94-5			0.35%	0.0262	0.0170%	3500		
		auxiliaries : additives	Trade Secret			0.35%	0.0262	0.0170%	3500		
		SiO2 Compounds	Trade Secret			0.50%	0.0375	0.0244%	5000		
		Phthalocyanine Green G	Trade Secret			0.50%	0.0375	0.0244%	5000		
		organic pigments	Trade Secret			0.50%	0.0375	0.0244%	5000		
		Epoxy resins	Trade Secret			22.85%	1.7126	1.1128%	228500		
		organic fillers	Trade Secret			0.35%	0.0262	0.0170%	3500		
		Nickel plate	1.50			Nickel	7440-02-0	100.000%	1.4979	0.9735%	1000000
		Gold plating	0.12			Gold	7440-57-5	100.000%	0.1212	0.0788%	1000000
		3	Compound			CEL-9750ZHF	71.69	Epoxy Resin(1)	Trade secret	4.00%	2.8676
Epoxy Resin(2)	Trade secret							3.00%	2.1507	1.3977%	30000
Hardener(1)	Trade Secret							4.00%	2.8676	1.8636%	40000
Hardener(2)	Trade Secret							4.00%	2.8676	1.8636%	40000
Carbon Black	1333-86-4							0.20%	0.1434	0.0932%	2000
Silica Oxide	60676-86-0							80.80%	57.9255	37.6447%	808000
Crystal Silicon	14808-60-7							4.00%	2.8676	1.8636%	40000
4	Epoxy/Die Adhesive			2025D	1.9			Diethylene glycol monoethyl ether acetate	112-15-2	35.00%	0.6650
		Rubber modified epoxy	TS ref# 10004			35.00%	0.6650	0.4305%	350000		
		Carbamate resin	TS ref# 10063			5.00%	0.0950	0.0615%	50000		
		Bismaleimide resin	TS ref# 10084			5.00%	0.0950	0.0615%	50000		
		Others	Not disclosure			20.00%	0.3800	0.2460%	200000		
		5	Gold Wire			2N	0.77	Gold	7440-57-5	100.0000%	0.7700
6	Solder Ball	M705	15.8	Tin	7440-31-5	96.50%	15.2470	9.9106%	965000		
				Silver	7440-22-4	3.00%	0.4740	0.3081%	30000		
				Copper	7440-50-8	0.50%	0.0790	0.0514%	5000		